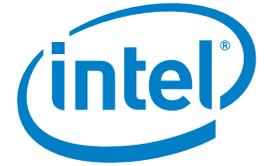


PRODUCT BRIEF

Intel® Desktop Board DQ67SW
Executive Series



MicroATX Form Factor

Intel® Desktop Board DQ67SW Executive Series



Built for Business

In today's competitive office environment, PC up-time is critical to business success. The Intel® Desktop Board DQ67SW is engineered to provide a stable and reliable platform that enhances office productivity with remote manageability and data security features. Based on the new Intel® Q67 Express Chipset with built-in Intel® Active Management Technology¹ 7.0, the Intel Desktop Board DQ67SW supports 2nd gen Intel® Core™ vPro™ processors in the latest LGA1155 package—bringing you unprecedented business PC performance. Abundant expandability options are available in the Intel Desktop Board DQ67SW, including two SuperSpeed USB 3.0 ports, dual independent display via DisplayPort*, DVI-D, and DVI-I graphic ports², six SATA ports including two SATA 6.0 Gb/s ports, one PCI Express 2.0 x4 connector, and one PCI Express 2.0 x16 graphics connector.

Seamless PC Remote Manageability

The Intel Desktop Board DQ67SW is equipped with improved KVM Remote Control manageability, enabling remote access and control of a PC, even when the PC is in OOB (out-of-band) state. Desk-side troubleshooting is greatly reduced with KVM Remote Control, saving both time and money.

Data Security Features

Protect sensitive office data with RAID built into the Intel Q67 Express Chipset, with multiple configurations to support RAID 0, 1, 5, and 10. Encryption and signature keys are protected from software-based attacks with onboard Trusted Platform Module (TPM).³ Also included in the Intel Desktop Board DQ67SW is the award-winning antivirus software ESET* Smart Security 4 with a one-year license.

Eco-Smart Computing

The Intel Desktop Board DQ67SW supports Phase-Shedding Technology, which allows it to shut down unneeded phases to enhance energy efficiency for significant power savings. The Intel Desktop Board DQ67SW meets ENERGY STAR*, ErP, and EPEAT* compliance standards and is RoHS-compliant to requirements for hazardous material reduction.

Multiple Operating System Certifications

The Intel Desktop Board DQ67SW is certified with the following operating systems: Windows* 7, Windows Vista* Premium, openSUSE*, and RedHat* Linux*.



Intel® Desktop Board DQ67SW Executive Series

The boxed Intel® Desktop Board DQ67SW solution includes:

- ATX 2.2 compliant I/O shield
- SATA cables
- Board and back panel I/O layout stickers
- Quick reference guide
- Intel® Express Installer driver and software DVD

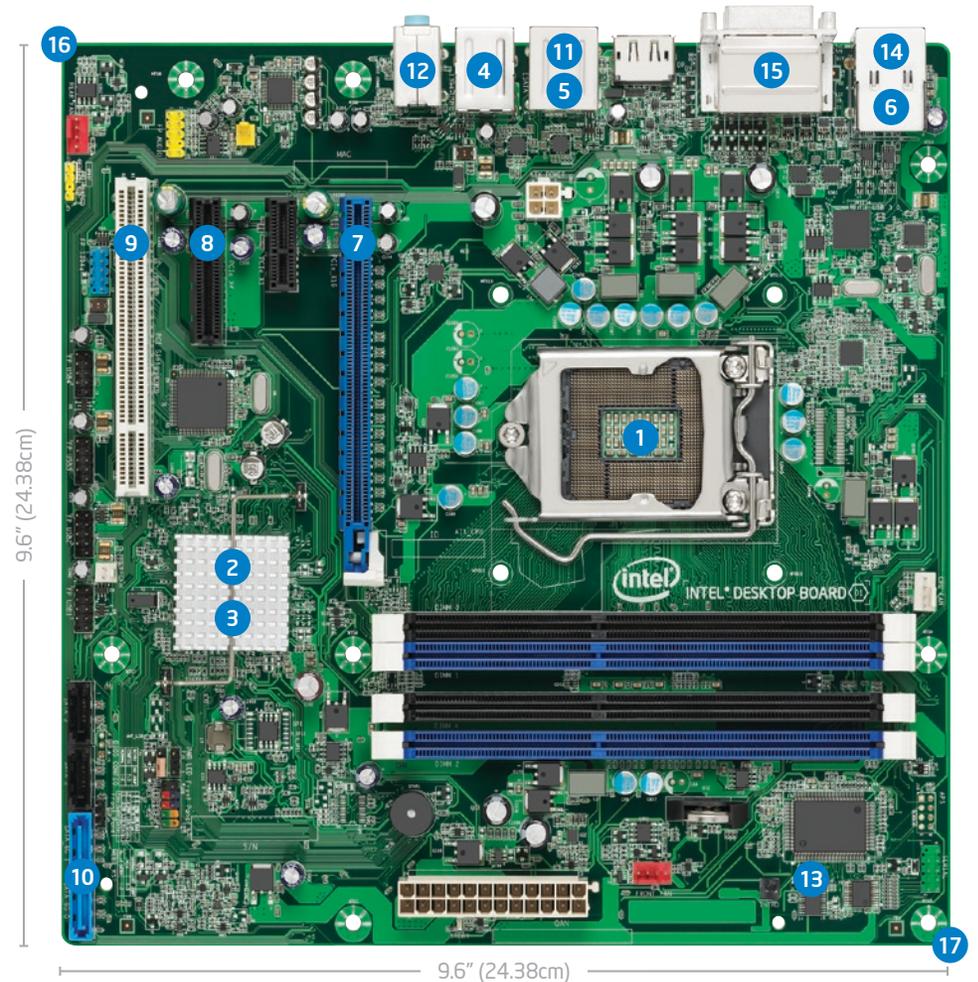
Software included:

CAPABILITY	SOFTWARE INCLUDED:
Utilities	<ul style="list-style-type: none">▪ Intel® Core Utilities Bundle⁴▪ Intel® Desktop Utilities
Security	<ul style="list-style-type: none">▪ ESET* Smart Security 4 (one-year license)▪ Wave* EMBASSY* Security Center
Manageability	<ul style="list-style-type: none">▪ RealVNC* Viewer Plus (Internet download)▪ Spiceworks* IT Desktop
Productivity	<ul style="list-style-type: none">▪ Laplink* PCmover* Professional

Intel® Desktop Board DQ67SW Executive Series

Features and Benefits

- 1 Support for the Intel® Core™ i7 vPro™, Intel® Core™ i5 vPro™, and Intel® Core™ i3 processors in the LGA1155 package: Features Intel® Turbo Boost Technology⁵ and Intel® Hyper-Threading Technology⁶ for exceptional performance and scalability.
- 2 Intel® Q67 Express Chipset
- 3 Integrated Memory Controller (IMC): Four connectors designed to support up to 32 GB⁷ dual-channel DDR3 1333 / 1066 MHz memory.
- 4 Two IEEE 1394a ports (one via internal header)
- 5 Twelve USB 2.0 ports (four back panel ports and eight additional ports via internal headers)
- 6 Two SuperSpeed USB 3.0 ports: 5.0 Gb/s signaling rate for high-speed connections to peripherals.
- 7 One PCI Express* 2.0 x16 graphics connector
- 8 One PCI Express 2.0 x4 connector
- 9 One PCI connector and one PCI Express 2.0 x1 connector
- 10 Two SATA 6.0 Gb/s ports and two SATA 3.0 Gb/s ports with Intel® Rapid Storage Technology: RAID 0, 1, 5, and 10.
- 11 Two eSATA 3.0 Gb/s ports
- 12 Eight-channel Intel® High Definition Audio⁸ with multi-streaming: Features internal S/PDIF output and front panel audio headers.
- 13 Trusted Platform Module (TPM)³: Delivers encryption and signature keys protection.
- 14 Intel® PRO 10/100/1000 Network Connection: Uses a new low-power design to meet improved ENERGY STAR* 5.0 specifications.
- 15 Dual independent display: Display-Port* + DVI-D + DVI-I graphics ports².
- 16 Lead-free: Meets all worldwide regulatory requirements for lead-free manufacturing.
- 17 MicroATX Form Factor: MicroATX board supports smaller tower and system designs.



Intel® Desktop Board DQ67SW Executive Series

Technical Specifications

PROCESSOR

Processor Support

- 2nd gen Intel® Core™ i7 vPro™, Intel® Core™ i5 vPro™, and Intel® Core™ i3 processors in the LGA1155 package
- Intel® Turbo Boost Technology⁵
- Intel® Hyper-Threading Technology⁶
- Integrated Memory Controller with support for up to 32 GB² of system memory using DDR3 1333 / 1066 MHz
- Intel® Fast Memory Access
- Supports Intel® 64 Architecture⁹

CHIPSET

Intel® Q67 Express Chipset

- Intel® 82Q67 Platform Controller Hub (PCH)
- Intel® Active Management Technology¹ 7.0
- Intel® Rapid Storage Technology (RAID 0, 1, 5, 10)

Integrated Intel® PCH Controllers

- Six Hi-Speed USB 2.0 ports
- Six additional ports via internal headers
- Two SATA 6.0 Gb/s ports and four SATA 3.0 Gb/s ports

System BIOS

- 32 Mb Flash EEPROM with Intel® Platform Innovation Framework for EFI Plug and Play, IDE drive auto-configure
- Advanced configuration and power interface V1.0b, DMI 2.5
- Intel® Express BIOS update support

Hardware Management Features

- Processor fan speed control
- System chassis fan speed control
- Voltage and temperature sensing
- Fan sensor inputs used to monitor fan activity
- Power management support for ACPI 1.0b

Intel® 82579LM ENERGY STAR*-ready Intel® PRO 10/100/1000 Network Connection

- High quality and reliability with Intel's world-class manufacturing and validation
- New low-power design

Expansion Capabilities

- One PCI Express* 2.0 x16 connector
- One PCI Express 2.0 x4 connector
- One PCI Express x1 connector
- One PCI connector

Audio

- Eight-channel Intel® High Definition Audio⁸ with multi-streaming
- One front panel audio header
- One internal S/PDIF output header

SYSTEM MEMORY

Memory Capacity

- Four 240-pin DIMM connectors supporting up to four double-sided DIMMs

Memory Types

- DDR3 1333 / 1066 SDRAM memory support
- Non-ECC Memory

Memory Voltage

- Memory voltage control from 1.2 V to 1.8 V
- 1.5 V standard JEDEC voltage

JUMPERS AND FRONT-PANEL CONNECTORS

Jumpers

- Single configuration jumper design
- Jumper access for BIOS maintenance mode

depending on the specific hardware and software you use. For more information including details on which processors support HT Technology, see www.intel.com/info/hyperthreading.

⁷ System resources and hardware (such as PCI and PCI Express*) require physical memory address locations that can reduce available addressable system memory. This could result in a reduction of as much as 1 GB or more of physical addressable memory being available to the operating system and applications, depending on the system configuration and operating system.

⁸ Intel® High Definition Audio requires a system with an appropriate Intel® chipset and a motherboard with an appropriate codec and the necessary drivers installed. System sound quality will vary depending on actual implementation, controller, codec, drivers, and speakers. For more information about Intel® HD Audio, refer to www.intel.com/design/chipsets/haudio.htm.

⁹ 64-bit computing on Intel® architecture requires a computer system with a processor, chipset, BIOS, operating system, device drivers, and applications enabled for Intel® 64 architecture. Processors will not operate (including 32-bit operation) without an Intel 64 architecture-enabled BIOS. Performance will vary

For ordering information, visit www.intel.com

For the most current product information, visit www.intel.com/go/idb or <http://ark.intel.com>

For specific processor compatibility, visit <http://processormatch.intel.com>

Front-Panel Connectors

- Reset, HD LED, Power LEDs, power on/off
- Four front panel Hi-Speed USB 2.0 headers
- Front panel audio header
- Front panel IEEE 1394a header

MECHANICAL

Board Style

- MicroATX

Board Size

- 9.6" x 9.6" (24.38cm x 24.38cm)

Baseboard Power Requirements

- ATX 12 V

ENVIRONMENT

Operating Temperature

- 0° C to +55° C

Storage Temperature

- -20° C to +70° C

REGULATIONS AND SAFETY STANDARDS

United States and Canada

- UL 1950, Third edition—CAN/CSA C22.2
- No. 950-95 with recognized U.S. and Canadian component marks

Europe

- Nemko certified to EN 60950 International
- Nemko certified to IEC 60950 (CB report with CB certificate)

EMC regulations (tested in representative chassis)

United States

- FCC Part 15, Class B
- FCC Part 15, Class B open-chassis (cover off) testing

depending on your hardware and software configurations. See <http://developer.intel.com/technology/intel64/index.htm> for more information.

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Canada

- ICES-003, Class B

Europe

- EMC directive 89/336/EEC; EN 55022:1998 Class B; EN 55024:1998

Australia/New Zealand

- AS/NZS 3548, Class B

Taiwan

- CNS 13438, Class B International
- CISPR 22:1997, Class B

Power requirements vary. Complies with US CRF via EN55022 +6 db in system configurations with an open chassis and EU Directive 89/336/EEC and use via EN55022 and EN50082-1 in a representative chassis.



Lead-Free: The symbol is used to identify electrical and electronic assemblies and components in which the lead (Pb) concentration level in any of the raw materials and the end product is not greater than 0.1% by weight (1000 ppm). This symbol is also used to indicate conformance to lead-free requirements and definitions adopted under the European Union's Restriction on Hazardous Substances (RoHS) directive, 2002/95/EC.

¹ Intel® Active Management Technology (Intel® AMT) requires the computer to have an Intel® AMT-enabled chipset, network hardware and software, connection with a power source, and a network connection.

² Requires the use of a processor with Intel® HD Graphics.

³ The original equipment manufacturer must provide TPM functionality, which requires a TPM-supported BIOS. TPM functionality must be initialized and may not be available in all countries.

⁴ The Intel® Core Utilities Bundle includes Intel® Integrator Assistant, Intel® Integrator Toolkit, Intel® Express Installer, and Intel® Express BIOS Update.

⁵ Intel® Turbo Boost Technology requires a PC with a processor with Intel Turbo Boost Technology capability. Intel Turbo Boost Technology performance varies depending on hardware, software, and overall system configuration. Check with your PC manufacturer on whether your system delivers Intel Turbo Boost Technology. See www.intel.com/technology/turboboost for more information.

⁶ Intel® Hyper-Threading Technology requires a computer system with a processor supporting HT Technology and an HT Technology-enabled chipset, BIOS, and operating system. Performance will vary

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